

AMENDMENTS TO THE CLAIMS

The listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. **(Previously Presented)** A variable adaptive mask for use with a physical vapor deposition process, comprising:
 - a fixed mask portion that comprises a top layer and a bottom layer;
 - a plurality of channels extending through the fixed mask portion;
 - a first plurality of wires positioned on the bottom layer, each wire of the first plurality of wires being disposed in a substantially spiral arrangement about a respective channel;
 - a second plurality of wires positioned on the top layer, each wire of the second plurality of wires being disposed in a substantially spiral arrangement about a respective channel; and
 - means for mounting the mask in a fixed position relative to a solid target material and a substrate.
2. **(Canceled)**
3. **(Original)** The mask of claim 1, wherein the channels have a circular profile.
4. **(Original)** The mask of claim 1, wherein the channels have a rectangular profile.
5. **(Canceled)**

6. **(Previously Presented)** The mask of claim 1, wherein the wires generate a magnetic field in the channels when electrical current is passed through the wires.

7. **(Currently amended)** The mask of claim ~~[[1]]~~6, wherein the wires are electrically connected to a computer or integrated circuit such that the magnetic field can be precisely controlled.

8. **(Original)** The mask of claim 1, further comprising a hard ferromagnetic material placed within the channels.

9. **(Withdrawn)** The mask of claim 1, wherein the means for controlling throughput comprises strips of material adjacent to the channels and having a high coefficient of thermal expansion such that the material reacts to heat by expanding.

10. **(Original)** The mask of claim 1, wherein the means for mounting comprises at least one mounting hole in the fixed mask portion.

11. **(Original)** The mask of claim 1, further comprising a calibration scale on the fixed mask portion.

12. **(Currently amended)** A variable adaptive mask for use with a physical vapor deposition process, comprising:

a fixed mask portion including a calibration scale;

a plurality of channels extending through the fixed mask portion;

a plurality of wires positioned on the fixed mask portion, each wire of the plurality of wires being disposed in a substantially spiral arrangement about a respective channel; and

one or more mounting holes for mounting the mask in a fixed position relative to a solid target material and a substrate.

13. **(Original)** The mask of claim 12, wherein the channels are defined by a top layer and a bottom layer of the fixed mask portion.

14. **(Canceled)**

15. **(Previously Presented)** The mask of claim 12, wherein the wires generate a magnetic field in the channels when electrical current is passed through the wires.

16. **(Currently amended)** The mask of claim ~~[[12]]~~**15**, wherein the wires are electrically connected to a computer or integrated circuit such that the magnetic field can be precisely controlled.

17. **(Original)** The mask of claim 12, further comprising a hard ferromagnetic material placed within the channels.

18. **(Cancelled).**

19. **(Withdrawn)** A variable adaptive mask for use with a physical vapor deposition process, comprising:
- a fixed mask portion;
 - a plurality of channels extending through the fixed mask portion;
 - a thermal control mechanism configured to control throughput of a vaporized target material through the channels; and
- one or more mounting holes for mounting the mask in a fixed position relative to a solid target material and a substrate.
20. **(Withdrawn)** The mask of claim 19, wherein the channels have a rectangular profile.
21. **(Withdrawn)** The mask of claim 19, wherein the thermal control mechanism comprises strips of material adjacent to the channels and having a high coefficient of thermal expansion such that the material reacts to heat by expanding.
22. **(Withdrawn)** The mask of claim 19, further comprising a calibration scale on the fixed mask portion.

23. **(Withdrawn)** A method of controlling a physical vapor deposition process, comprising:
providing a variable adaptive mask comprising:
a fixed mask portion;
a plurality of channels extending through the fixed mask portion; and
a magnetic control mechanism configured to control throughput of a vaporized target material through the channels;
generating a magnetic field in the channels;
directing vaporized target material particles toward the channels such that the particles are affected by the magnetic field which causes a portion of the particles to bend away from a central portion of the channels toward an edge of the channels, wherein the throughput of the vaporized target material particles is proportional to the magnitude of the magnetic field.
24. **(Withdrawn)** The method of claim 23, wherein the magnetic control mechanism comprises wires wrapped in a spiral configuration around each of the channels.
25. **(Withdrawn)** The method of claim 24, wherein the wires generate the magnetic field in the channels when electrical current is passed through the wires.
26. **(Withdrawn)** The method of claim 24, wherein the wires are electrically connected to a computer or integrated circuit such that the magnetic field can be precisely controlled.

27. **(Withdrawn)** A method of controlling a physical vapor deposition process, comprising:
providing a variable adaptive mask comprising:
a fixed mask portion;
a plurality of channels extending through the fixed mask portion; and
a thermal control mechanism configured to control throughput of a vaporized target material through the channels; and
directing vaporized target material particles toward the channels, wherein the throughput of the vaporized target material particles is proportional to the heat applied to the adaptive mask.
28. **(Withdrawn)** The method of claim 27, wherein the thermal control mechanism comprises strips of material adjacent to the channels and having a high coefficient of thermal expansion such that the material reacts to heat by expanding.